



General Description

The MAX97236 is an audio amplifier with volume control and microphone preamplifier intended for use in portable audio systems employing a headphone jack. The audio circuit is powered from a single, dual-mode charge pump, allowing the output signals to be ground referenced, and eliminating the need for large and expensive DC-blocking capacitors. The configuration of a 3.5mm jack is determined by autoconfigure circuitry. The IC's functional blocks are auto-enabled after the configuration of the jack is determined.

The audio amplifier is powered from a single 1.8V power supply that reduces overall power consumption. The microphone preamplifier and bias are powered from a separate power-supply input accommodating bias voltages that are greater than 2.4V.

The automatic jack detection determines when a 3.5mm plug is inserted into the system jack and determines the configuration of the installed load. The configuration of the load is then reported to the system through the I2C interface. Multiple popular jack and load configurations are detectable with this scheme. The IC detects headsets, headphones, and A/V cables.

The headphone amplifier is capable of over 35mW into 16 Ω . The device is available in a small. 25-bump WLP package with a 0.4mm pitch and is specified over the extended -40°C to +85°C temperature range.

Applications

Smartphones

Mobile Handsets

Notebooks

Portable Gaming Devices

Tablets

Ordering Information

PART	TEMP	PIN-	I ² C
	RANGE	PACKAGE	ADDRESS
MAX97236EWA+	-40°C to +85°C	25 WLP	0x80

⁺Denotes a lead(Pb)-free/RoHS-compliant package.

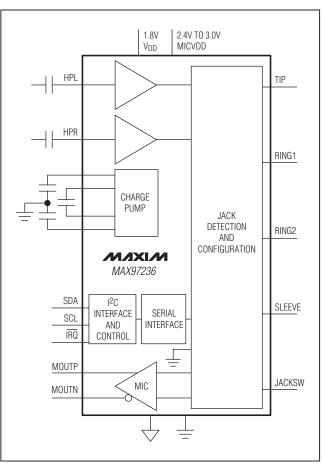
Functional Diagram/Typical Application Circuit appears at end of data sheet

Features

- ♦ 30mW Headphone Amplifier Employs Second-Generation DirectDrive® with Dual-Mode Charge-**Pump Architecture**
- **♦ Automatic Jack Detection Circuitry**
- **♦ Microphone Amplifier and Bias**
- ♦ 1.8V Power Supply
- ♦ 2.4V to 3.6V Microphone Power Supply
- **♦ Headphone Amplifier Volume Control**
- ♦ Decodes Data from a Passive Multibutton Headset **Remote Control**
- ♦ 25-Bump, 2.4mm x 2.3mm, 0.4mm Pitch WLP

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Simplified Block Diagram



/U/IXI/U

Maxim Integrated Products 1

ABSOLUTE MAXIMUM RATINGS

V _{DD} to PGND0.3V to +2V MICVDD to PGND0.3V to +5.5V	MOUT+ and MOUT- to PGND0.3V to (VMICVDD + 0.3V) C1P to PGND0.3V to (VPVDD + 0.3V)
PVDD to PGND0.3V to (V _{DD} + 0.3V) PVSS to PGND2V to +0.3V	C1N to PGND(VPVSS - 0.3V) to +0.3V SDA, SCL, EXTCLK, and IRQ to PGND0.3V to +6V
GND to PGND0.1V to +0.1V	Output Short-Circuit Duration
TIP, RING1, IN_ to PGND(VPVSS - 0.3V)	Continuous Power Dissipation (Mulitlayer Board, TA = +70°C)
to $(VPVDD + 0.3V)$	25-Bump WLP (derate 19.2mW/°C above +70°C)1536mW
RING2, SLEEVE to PGND(GND - 0.3V)	Junction Temperature+150°C
to $(V_{MICVDD} + 0.3V)$	Operating Temperature Range40°C to +85°C
JACKSW to PGND(VPVSS - 0.3V) to (VMICVDD + 0.3V)	Storage Temperature Range65°C to +150°C
MBIAS to PGND0.3V to (VDD + 0.3V)	Soldering Temperature (reflow)+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

PACKAGE THERMAL CHARACTERISTICS (Note 1)

Junction-to-Ambient Thermal Resistance (θ_{JA})......52°C/W

Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to www.maxim-ic.com/thermal-tutorial.

ELECTRICAL CHARACTERISTICS

 $(V_{DD} = 1.8V, V_{MICVDD} = 3.0V, V_{GND} = V_{PGND} = 0V, C_{FLY} = C_{PVDD} = C_{PVSS} = 1\mu F.$ Typical values tested at T_A = +25°C, unless otherwise noted. See the *Functional Diagram/Typical Application Circuit.*) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
GENERAL	•					
Supply Voltage Range	V _{DD}	Guaranteed by PSRR test	1.62	1.8	1.98	V
Undervoltage Lockout	UVLO	Rising V_{DD} , $T_A = +25^{\circ}C$			1.6	V
Chutdown Cupply Current	I _{VDD_SDF}	In jack detect mode, T _A = +25°C, fast detect mode, external clock disabled		14	25	
Shutdown Supply Current	I _{VDD_SDS}	In jack detect mode, T _A = +25°C, slow detect mode, external clock disabled		14	25	μΑ
Sleep Supply Current	I _{VDD_SL}	T _A = +25°C, external clock disabled			25	μΑ
Quiescent Supply Current	I _{VDD}	T _A = +25°C, state = LRGM		2.3	3.9	mA
SDA, SCL Input Logic-High	V _{IH}	1.8V logic compliant	1.4			V
SDA, SCL Input Logic-Low	V _{IL}	1.8V logic compliant			0.4	V
SDA, SCL, EXTCLK Input Leakage Current High	I _{IH}	$T_A = +25^{\circ}C$	-1		+1	μΑ
SDA, SCL, EXTCLK Input Leakage Current Low	I _{IL}	T _A = +25°C	-1		+1	μΑ
SDA, SCL Output Logic-Low	V _{OLI2C}	I _{OLI2C} = 2.3mA		0.2 x V _{DD}		V
IRQ Output High Current	ГОН	$V_{IRQ_OUT} = 3.3V, T_A = +25^{\circ}C$			1	μΑ
IRQ Output Logic-Low	V _{OL}	I _{OL} = 3mA			0.25 x V _{DD}	V

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{DD} = 1.8V, V_{MICVDD} = 3.0V, V_{GND} = V_{PGND} = 0V, C_{FLY} = C_{PVDD} = C_{PVSS} = 1\mu F.$ Typical values tested at TA = +25°C, unless otherwise noted. See the *Functional Diagram/Typical Application Circuit.*) (Note 2)

PARAMETER			MIN	TYP	MAX	UNITS
EXTCLK Input High Voltage			1.4			V
EXTCLK Input Low Voltage					0.4	V
EXTCLK Frequency Range	f _{EXTCLK}	$T_A = +25^{\circ}C$	1	19.2	26	MHz
EXTCLK Duty Cycle	D_EXTCLK	$T_A = +25^{\circ}C$	45		55	%
Maximum EVTCL // Clay Bata		f _{EXTCLK} = 1MHz, 0.4V to 1.4V		50		20
Maximum EXTCLK Slew Rate		f _{EXTCLK} = 10MHz, 0.4V to 1.4V		5		ns
Turn-On Time	t _{ON}	(Note 3)		1	10	ms
JACK DETECTION						
Turn-On Time	^t ONTIME	Jack detect time from insertion to interrupt (Note 4)		500		ms
AUDIO AMPLIFIER (Gain = 0dB,	Unless Otherw	ise Noted)				
Output Offset Voltage	V _{OS}	$T_A = +25$ °C, state = LRGM	-500		+500	μV
Output Power	D	$R_L = 32\Omega$, $THD+N = 1\%$, $f_{IN} = 1$ kHz		30		m\//
Output Power	P _{OUT}	$R_L = 16\Omega$, $THD+N = 1\%$, $f_{IN} = 1$ kHz		35		mW
Line Output Voltage	V _{O_LINE}	$R_L = 10k\Omega$		1		V _{RMS}
T		$R_L = 16\Omega$, $P_{OUT} = 10$ mW, $f_{IN} = 1$ kHz		0.05		
Total Harmonic Distortion Plus Noise	THD+N	$R_L = 16\Omega$, $P_{OUT} = 0.1$ mW, $f_{IN} = 1$ kHz		0.04		%
T lus Noise		$R_L = 10k\Omega$, $V_{OUT} = 1V_{RMS}$, $f_{IN} = 1kHz$		0.03		
	ONE	Referenced to 32Ω load, $1V_{RMS}$ input signal, A-weighted	103			
Signal-to-Noise Ratio	SNR	Referenced to 32Ω load, $1V_{RMS}$ input signal, A-weighted (gain = -30dB)	85			dB
		DC 1.62V to 1.98V, gain = 0dB, T _A = +25°C		87		
Power-Supply Rejection Ratio	PSRR	f _{IN} = 217Hz, 100mV _{P-P} ripple, gain = 0dB	78			dB
		f _{IN} = 10kHz, 100mV _{P-P} ripple, gain = 0dB	74			
		A-weighted		6		
Output Noise	V _N	A-weighted, gain = -30dB		1.7		μV _{RMS}
		A-weighted, gain = -60dB		1.4		
Peak Output Current	lout	Peak current needed to output the rated typical power		40		mA
Minimum Headphone Impedance	Z _{OUT}			12		Ω
		$R_L = 16\Omega$, $f_{IN} = 1$ kHz, $P_{OUT} = 5$ mW, crosstalk between audio channels, gain = 0dB, with ground sense	-51			dB
Crosstalk	XTALK	$R_L = 32\Omega$, $f_{IN} = 1$ kHz, $P_{OUT} = 25$ mW, crosstalk between audio channels, gain = 0dB, with ground sense	-56			dB

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{DD} = 1.8V, V_{MICVDD} = 3.0V, V_{GND} = V_{PGND} = 0V, C_{FLY} = C_{PVDD} = C_{PVSS} = 1\mu F.$ Typical values tested at T_A = +25°C, unless otherwise noted. See the *Functional Diagram/Typical Application Circuit.*) (Note 2)

PARAMETER	SYMBOL	CONDITIONS			MIN	TYP	MAX	UNITS
		$R_L = 10k\Omega$,	gain ≥ 0dB			470		
Maximum Capacitive Load Drive	C_L	$R_L = 10k\Omega$,	gain < 0dB			200		рF
		$R_L = 32\Omega$				200		
			$P_{OUT} = 0.$	5mW, $R_L = 32\Omega$		4.5		
Power Consumption		Pout = $4.5r$ Per channel (Note 5)		5mW, $R_L = 32\Omega$,		6.8		mW
·			P _{OUT} = 20 (Note 6)	OmW, $R_L = 32\Omega$,		23		
		Output voltage needed THSH = 0		THSH = 0		0.4		
Charge-Pump Switch Threshold		to toggle the	charge-	THSH = 1		0.55		V
Click-and-Pop Level	KCP	$R_L = 32\Omega$, p	$R_L = 32\Omega$, peak voltage, A-weighted,			-74		dBV
olicit and 1 op 20vol	ROI	32 samples/		Out of shutdown		-74		GBV
Input Capacitance	C _{IN}	Gain = 6dB				150		рF
Input Impedance	Z _{IN}				16		75	kΩ
AUDIO AMPLIFIER VOLUME CON			-					
Gain Range		From min to	max volum	e setting	-60		+6	dB
Maximum Volume Setting					5.5	6	6.5	dB
Minimum Volume Setting					-60.5	-60	-59.5	dB
Mute Attenuation						80		dB
Channel-to-Channel Gain Matching					-0.5		+0.5	dB
		Volume setti	na -54dB <	_VOL ≤ 6dB		1		
Gain Change per Step				 VOL ≤ -54dB		2		dB
MICROPHONE BIAS		1						
MIC Bias Supply Voltage	V _{MICVDD}	Guaranteed	by MIC bia	s PSRR test	2.4		3.6	V
		High output			2.4	2.6	2.8	
Bias Output Voltage	V_{BIAS}	Low output v			1.84	2	2.16	V
Bias Output Current	I _{BIAS_OUT}	R _{MICBIAS} = voltage, T _A :		(2.6V) output	1.2			mA
MIC Supply Current Consumption	I _{MBIAS}					150	400	μΑ
		$MICR = 0b0$ $T_A = +25^{\circ}C$	0, V _{MBIAS} =	= 2.6V,	2.02	2.2	2.38	
Di O I I D I I	0	$MICR = 0b0$ $T_A = +25^{\circ}C$	2.39	2.6	2.81	1.0		
Bias Output Resistance	R _{MBIAS}	$MICR = 0b1$ $T_A = +25^{\circ}C$	MICR = 0b10, V _{MBIAS} = 2.6V,				3.24	kΩ
		$MICR = 0b1$ $T_A = +25^{\circ}C$	1, V _{MBIAS} =	= 2.6V,		0.07		
Bias Output Noise	V _{N_BIAS}	With externa	l capacitor	, V _{MBIAS} = 2.6V		2.8		μV _{RMS}

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{DD} = 1.8V, V_{MICVDD} = 3.0V, V_{GND} = V_{PGND} = 0V, C_{FLY} = C_{PVDD} = C_{PVSS} = 1\mu F.$ Typical values tested at TA = +25°C, unless otherwise noted. See the *Functional Diagram/Typical Application Circuit.*) (Note 2)

PARAMETER	SYMBOL	CONDITIONS			TYP	MAX	UNITS
Bias Power-Supply Rejection	PSRR _{MBIAS}	D	$V_{MICVDD} = 2.4V \text{ to}$ 3.6V, $T_A = +25^{\circ}C$	74	90		dB
Bias i ower-supply riejection	1 SHIMBIAS	$R_{MBIAS} = 2.2k\Omega$	$f_{IN} = 2kHz$, $100mV_{P-P}$ ripple		75		QD.
MICROPHONE PREAMPLIFIER							
MIC Prooms Coin	A	Gain = high, f _{IN} =	997Hz	23	24	25	dB
MIC Preamp Gain	Аміс	Gain = low, f _{IN} =	997Hz	11	12	13	ub
Supply Current Consumption	I _{DD_MAMP}				200	300	μA
MIC Preamp Noise	V _{N_MAMP}	Input referred (No A-weighted 0.1kH	ote 7), gain = 24dB, Iz to 7kHz		3		μV
Total Harmonic Distortion Plus Noise	THD+N _{MICPRE}	f _{IN} = 1kHz, V _{IN} =	1V _{RMS}			3	%
Low Corner Frequency Response	f _{-3dB}	Relative to 997Hz			15		Hz
High Corner Frequency Response	f-3dB	Relative to 997Hz	_		> 300		kHz
MIC Preamplifier Power-Supply Rejection	PSR _{MAMP}		$V_{\text{MICVDD}} = 2.4 \text{V to } 3.6 \text{V}, T_{\text{A}} = +25 ^{\circ} \text{C},$ gain = +24dB, $R_{\text{MIC}} = 500 \Omega$		90		dB
The jection		$f_{IN} = 2kHz$, 100m		58			
Output Common-Mode Voltage	V _{CM_MIC}	Voltage measured MOUTN to GND	d from MOUTP or		0.8		V
Input Capacitance	C _{MAMP}	AC-coupling capa	acitance		85		pF
Input Resistance	R _{MAMP}	Input resistance			100		МΩ
Output Impedance	Z _{OUT}				10		Ω
6-BIT KEY ENCODER ADC							
ADC Trip Level		Level at which the trigger a conversi	e mic bias must drop to ion		0.64		V
Minimum ADC Course Range		LSB 10mV			0.128		V
Maximum ADC Course Range		LSB 10mV			0.64		V
Minimum ADC Fine Range		LSB 2mV		0		V	
Maximum ADC Fine Range		LSB 2mV			0.128		V
CHARGE PUMP							
Oscillator Frequency	fosc1	$V_{OUT} = 0V, R_L =$	open, T _A = +25°C	78	83	88	kHz
Osomator Frequency	f _{OSC2}	$V_{OUT} = 0.2V, R_L$	= open	665			I II

I²C TIMING CHARACTERISTICS

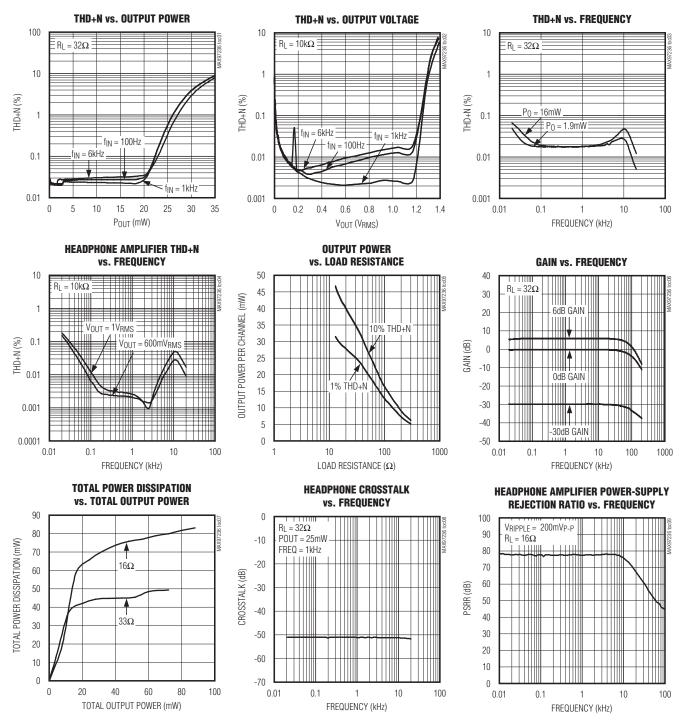
(TA = TMIN to TMAX, unless otherwise noted. Typical values are at TA = +25°C.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Serial-Clock Frequency	f _{SCL}		0		400	kHz
Bus Free Time Between STOP and START Conditions	t _{BUF}		1.3			μs
Hold Time (REPEATED) START Condition	t _{HD,STA}		0.6			μs
SCL Pulse-Width Low	t _{LOW}		1.3			μs
SCL Pulse-Width High	^t HIGH		0.6			μs
Setup Time for a REPEATED START Condition	t _{SU,STA}		0.6			μs
Data Hold Time	t _{HD,DAT}		0		900	ns
Data Setup Time	t _{SU,DAT}		100			ns
SDA and SCL Receiving Rise Time	t _R		20 + 0.1C _B		300	ns
SDA and SCL Receiving Fall Time	t _F		20 + 0.1C _B		300	ns
SDA Transmitting Fall Time	t _F		20 + 0.1C _B		250	ns
Setup Time for STOP Condition	t _{SU,STO}		0.6			μs
Bus Capacitance	C _B				400	pF
Pulse Width of Suppressed Spike	t _{SP}		0		50	ns

- Note 2: All specifications are 100% tested at T_A = +25°C. Temperature limits are guaranteed by design.
- **Note 3:** The current listed toN is the time from the system sending the enable signal, after receiving the DDONE signal, to when the amplifier outputs turn on.
- Note 4: Total turn-on time from jack insert to output enable is dependent upon the search algorithm.
- Note 5: Power consumption numbers taken with the THRH bit set high, fixing the power-supply switchover threshold at its highest value.
- **Note 6:** Power consumption numbers taken with the high efficiency bit set low, fixing the power-supply switchover threshold at its lowest value, providing the least amount of dynamic distortion.
- **Note 7:** Tested with R_{MIC} = $6k\Omega$ in parallel with 5pF connected from SLEEVE to RING2.

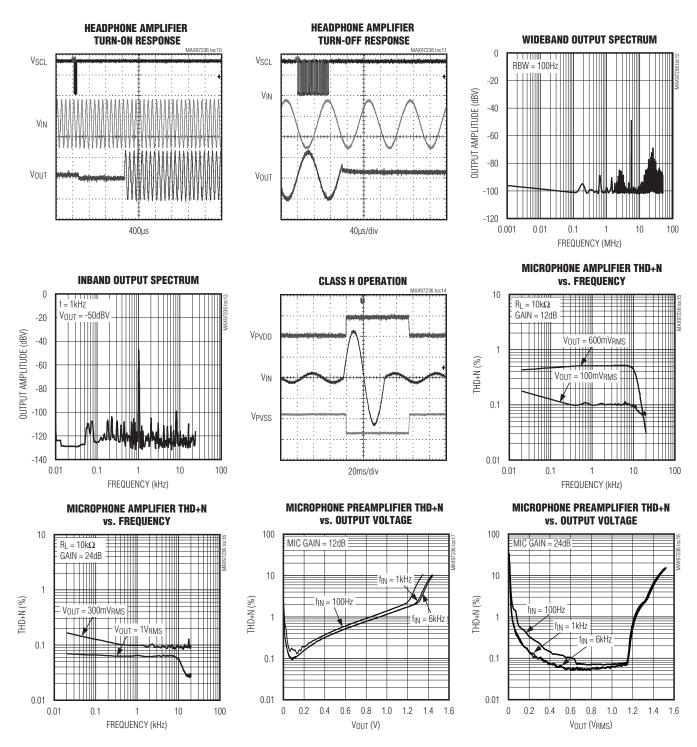
Typical Operating Characteristics

(VDD = 1.8V, VMICVDD = 3.0V, VGND = VPGND = 0V, CFLY = CPVDD = CPVSS = 1µF.)



Typical Operating Characteristics (continued)

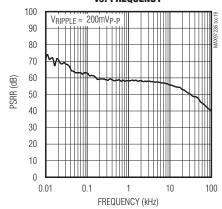
 $(V_{DD} = 1.8V, V_{MICVDD} = 3.0V, V_{GND} = V_{PGND} = 0V, C_{FLY} = C_{PVDD} = C_{PVSS} = 1\mu F.)$



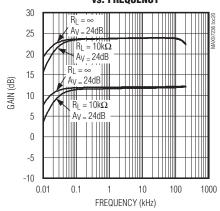
Typical Operating Characteristics (continued)

 $(V_{DD} = 1.8V, V_{MICVDD} = 3.0V, V_{GND} = V_{PGND} = 0V, C_{FLY} = C_{PVDD} = C_{PVSS} = 1\mu F.)$

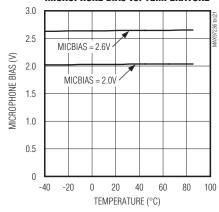
MICROPHONE PREAMPLIFIER POWER-SUPPLY REJECTION RATIO vs. FREQUENCY



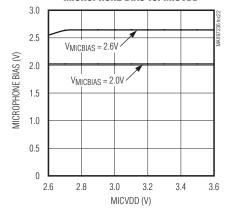
MICROPHONE AMPLIFIER GAIN vs. FREQUENCY



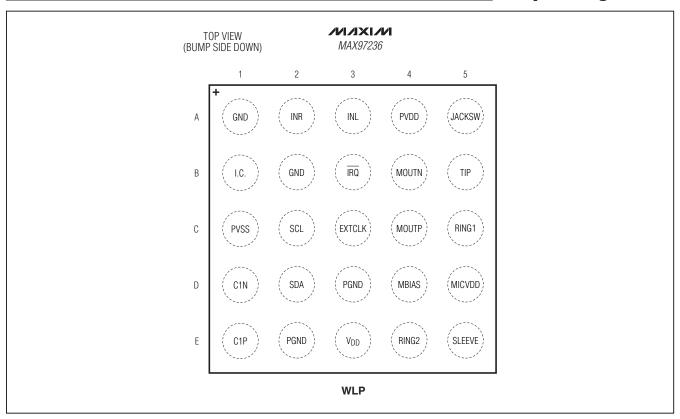
MICROPHONE BIAS vs. TEMPERATURE



MICROPHONE BIAS vs. MICVDD



Bump Configuration



Bump Description

BUMP	NAME	FUNCTION
A1, B2	GND	Analog Ground
A2	INR	Right Audio Input
А3	INL	Left Audio Input
A4	PVDD	Charge-Pump Positive Output. Bypass to PGND with 1µF.
A5	JACKSW	Jack Switch. Connect to the mechanical switch.
B1	I.C.	Internally Connected. Leave unconnected.
В3	ĪRQ	Interrupt Request Flag. Open-drain, active-low digital output. Pullup with $10k\Omega$ to system logic voltage.
B4	MOUTN	Negative Microphone Output
B5	TIP	Left Headphone Output. Connect to the tip of the four-pole jack.
C1	PVSS	Charge-Pump Negative Output. Bypass to PGND with 1µF.
C2	SCL	I ² C Serial-Clock Input
C3	EXTCLK	External System Clock Input. All internal digital clocks are derived from EXTCLK.

Pin Description (continued)

BUMP	NAME	FUNCTION
C4	MOUTP	Positive Microphone Output
C5	RING1	Jack Input 2/Right Headphone Output. Connect to the first ring of the four-pole jack.
D1	C1N	Charge-Pump Flying Capacitor Negative Connection. Connect 1µF between C1N and C1P.
D2	SDA	Serial-Data I/O
D3, E2	PGND	Power Ground. Ground Return for the charge pump.
D4	MBIAS	Microphone Bias Capacitor Connection. Connect 1µF to GND.
D5	MICVDD	Microphone Power-Supply Input. Bypass to GND with 1µF.
E1	C1P	Charge-Pump Flying Capacitor Positive Connection. Connect 1µF between C1N and C1P.
E3	V _{DD}	Main Power-Supply Input. Connect to 1.8V and bypass to GND with 1µF.
E4	RING2	Microphone Input Headset GND. Connect to the second ring of the four-pole jack.
E5	SLEEVE	Microphone Input Headset GND. Connect to the sleeve of the four-pole jack.

Detailed Description

Class H DirectDrive Headphone Amplifier with Dual-Mode Charge Pump

The headphone amplifier is optimized for low-power consumption and low noise. A charge pump generates a negative and positive supply voltage that powers the headphone amplifier and eliminates the need for a large output coupling capacitor.

The headphone amplifier has volume control from -60dB to +6dB. A single-pole filter, $f_{-3dB} = 85 \text{kHz}$, attenuates signals outside the audio band.

Dual-Mode Charge Pump

The charge pump powers the headphone amplifier. When a headphone load is connected and the audio output signal is small, the charge pump outputs a ± 0.9 V negative and positive supply voltage. When a large audio signal is applied, the output rails of the charge pump switch to a higher voltage mode, ± 1.8 V. The higher voltage rails accommodate the higher voltage swing necessary to amplify line level audio signals. The lower voltage rails reduce the power consumption of the headphone amplifier when higher rails are not needed.

Class H Operation

The Class H amplifier employs a class AB output stage with power-supply voltages that shift based on the output signal needs (Figure 1). The lower power supply rails are

used when the output voltage requirements are below the 0.5V threshold. The higher supply rails are used when the output voltage is above the 0.5V threshold, maximizing output power and voltage swing. The switch between available power-supply voltages occurs on a cycle-by-cycle basis.

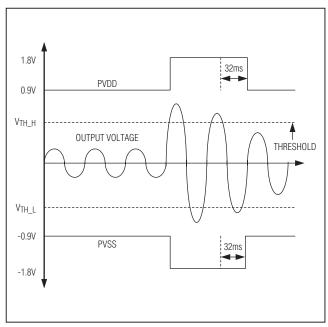


Figure 1. Class H Power-Supply Operation

Audio Short-Circuit Protection

A short on the right audio output does not shut down the left audio channel. A short on the left audio output does not shut down the right audio channel. This ensures that a mono audio plug does not damage the chip, but allows audio to be heard through the other channel output. A short is considered anything below 4Ω for a time period of 100ms.

Ground Sense

The headphone amplifier features output ground sensing for improved crosstalk performance. Crosstalk is improved by at least 20dB, between the audio channels, which all share a common jack ground. Figure 2 shows the audio signal path from the filter through the amplifier with volume control and the ground sense.

Headphone Amplifier Input Filter

The headphone amplifiers employ a lowpass filter to remove out-of-band noise from the audio DAC driving the headphone inputs. The filter attenuates frequencies above 85kHz.

Headphone Amplifier Volume Control

The IC features a 64-step volume control with a resolution of 1dB/step from +6dB down to -54dB and 2dB/step from -54dB to -60dB. <u>Figure 3</u> shows the I/O curve of the volume control.

Headphone Volume Slewing

Volume slewing breaks up large volume changes into the smallest available step size as it goes through each gain level between the initial and final volume setting. Volume

MAXIM
MAX97236

RING1
OR TIP

RING2
OR SLEEVE

PGND

Figure 2. Headphone Amplifier Signal Path

slewing also occurs at device turn-on and turn-off when enabled. During turn-on, the volume is set to mute before the output is enabled. Once the output is on, the volume ramps to the programmed level. At turn-off, the volume is ramped to mute before the output is disabled.

As briefly described in the last section, the $\overline{\text{VSEN}}$ (volume slew enable) bit decides whether each volume step is used when changing volume settings or whether the final volume setting jumps to the new value after writing. The volume slew enable function is used in conjunction with the zero-crossing detection enable ($\overline{\text{ZDEN}}$).

Examples:

VSEN = **0**, **ZDEN** = **0**, **both functions on:** The volume changes one gain step at a time. The gain only changes at the zero crossing of the audio signal.

VSEN = **0**, **ZDEN** = **1**: The volume changes one gain step at a time.

VSEN = 1, **ZDEN** = 0: New volume is asserted as soon as audio signal has gone through a zero crossing (or 100ms after the last gain change, whichever comes first).

 $\overline{\text{VSEN}}$ = 1, $\overline{\text{ZDEN}}$ = 1: New volume is asserted as soon as the I²C command is received.

Headphone Volume Zero-Crossing Detection

Zero-crossing detection is implemented on the headphone amplifier volume control to prevent large glitches when volume changes are made. Instead of making a volume change immediately when requested, the change is made when the audio signal has a zero crossing or after 100ms, whichever comes first.

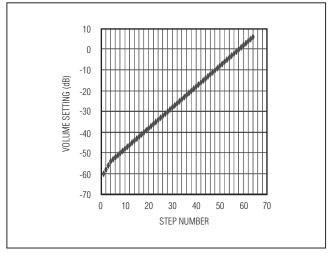


Figure 3. Headphone Volume Control Input/Output Transfer Function

Microphone Bias

The IC features a low-noise microphone bias generator and amplifier. The bias voltage resistors are selectable through I²C register 0x09.

Ensure that V_{MICVDD} is greater than the desired microphone bias voltage.

The microphone bias line is also used by passive single button and passive multibutton headsets.

Microphone Preamplifier

A microphone preamplifier provides an additional gain of 12dB or 24dB (programmable) with low input-referred noise and high power-supply rejection. Figure 4 shows the configuration of the microphone bias, amplifier, and microphone. Internal AC-coupling capacitors connect both the microphone output and also the MBIAS line to a differential amplifier, giving improved PSRR.

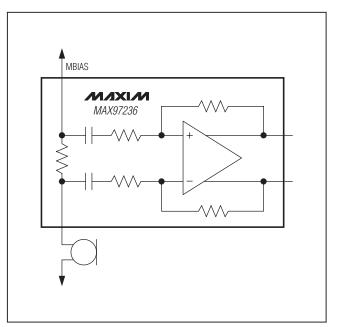


Figure 4. Microphone Preamplifier Simplified Schematic

Jack Detection and Configuration Algorithm

The IC features a detection scheme that senses when a 3.5mm plug is inserted into the system jack. After sensing insertion, a configuration detection algorithm takes over and reads the makeup of the installed plug. Information regarding the makeup of the plug is reported back through the I²C status registers. The device can also be placed in autoconfigure mode. This mode allows the IC to automatically enable the correct functional blocks depending upon the class of cable that has been inserted.

Jack Insertion Testing

The jack insertion detection uses an inaudible AC waveform output on the jack pins to sense when a load is plugged in. This electrical test is used to verify and work in conjunction with a mechanical switch (JACKSW). The mechanical switch, while not used as the main sensing mechanism, can be used to save system power. When a jack is plugged into a device, the switch at JACKSW is closed. When no jack is plugged in, the switch at JACKSW is working, the electrical polling of the jack can be done less often. A test is done every time a jack is sensed to check if the switch at JACKSW is working correctly. If the IC deems that the switch at JACKSW is broken, the system is flagged. At that point, the system can decide whether to ignore JACKSW results and poll more quickly.

Jack Configuration Detection

The jack detection and configuration is bounded by certain load resistance and capacitance limitations. The correct detection and configuration cannot be guaranteed outside those limitations. The limitations are shown in Table 1.

Table 2 shows each load case that is detectable with the IC's jack configuration algorithm and which class of cable is found. The status bits of the I²C register (0x01, 0x02, 0x03) report the load found during testing. The functional blocks are set automatically if AUTO = 10 or 01 (register 0x01E bits 0 and 1), according to what class of cable is detected.

Table 1. Jack Detection and Configuration Load Limits

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS
Cable Shield Capacitance	C _{CABLE}	150		500	рF
Headphone Load Resistance	R _{HP}	12		650	Ω
Headphone Load Inductance	L _{HP}	30		1600	μΗ
Audio Line Load Resistance	R _{LINE}	6		50	kΩ
Microphone Load Resistance	R _{MIC}	0.5		15	kΩ

Case 9 is a special case that requires subsequent testing of the load pins while servicing the left audio load that has been found. In this case only, the status bits report that a line level audio load had been found on TIP while tests continue to run on RING1 and SLEEVE. Once a load is found with one of the subsequent tests, enough information about the cable class is known to stop testing. The status bits reflect what is found, and the signal paths are configured according to the cable class and testing stops.

Detecting Jack Removal

There are two main jack removal detection methods: an electrical method and a mechanical method. The electrical

unplug detection method varies, depending on which load is plugged in. Cases with a microphone wait for the microphone bias to fly up to its full value. The audio only headphones wait for SLEEVE to fly up when the jack is removed.

For cases with an AV cable and audio only connected, the IC can only rely on JACKSW to sense removal or to wait for user input to shut down audio.

The electrical unplug detection (JKIN bit) is not available when the IC is running the jack configuration algorithm, when in FORCE mode, or when in test mode. In those cases, an unplug can only be detected mechanically through the JACKSW bit.

Table 2. Jack Configurations and Status Registers (After DDONE Bit Has Been Reset)

CASE	CABLE CLASS		PI	NS		JACKSW	REGISTER	REGISTER	REGISTER
NO.	CABLE CLASS	1	1 2 3 4		STATE	0x00	0x01	0x02	
1	Nothing	F	F	F	F	Short	0x00	0x00	0x00
2	Extension cable	С	С	С	С	Open	0x84	0x00	0x00
3	Stereo headset (headphones with microphone), GND on P3	L	R	G	М	Open	0x8C	0x30	0x01
4	Stereo headset (headphones with microphone), GND on P4	L	R	М	G	Open	0x8C	0x30	0x02
5	Line audio cable	L	R	G	G	Open	0x84	0xC0	0x03
6	Mono headset, GND on P3	L	G	G	М	Open	0x8C	0x20	0x01
7	Mono headset, GND on P4	L	G	М	G	Open	0x8C	0x20	0x02
8	Mono headset, GND on P3	L	L	G	М	Open	0x8C	0x20	0x01
9	Mono headset, GND on P4	L	L	М	G	Open	0x8C	0x20	0x02
10	Mono headset, GND on P3	L	F	G	М	Open	0x8C	0x20	0x01
11	Mono headset, GND on P4	L	F	М	G	Open	0x8C	0x20	0x02
12	Stereo headphones	L	L	G	G	Open	0x84	0x30	0x03
13	Stereo headphones, right channel open	L	F	G	G	Open	0x84	0x20	0x03
14	Stereo headphones, left channel open	F	L	G	G	Open	0x84	0x10	0x03

Key Switch Encoder

There are two types of keypads that can be connected to the IC:

- A single-button hook switch or MIC switch that grounds out the microphone bias when pressed
- A passive multibutton headset

Key Switch Encoder Timing

Two registers, 0x15 and 0x16, control the key switch debounce time, t_{DEB} , and delay time, t_{DELAY} .

The debounce time, 0x15, is the time from when the switch stops bouncing and when the ADC converts.

The delay time, 0x16, is set long to ensure that an unplug event is not encoded as a keypress. See Figure 9.

The PRESS Bit

The PRESS bit alerts the system to whether the current interrupt was caused by a button press or release.

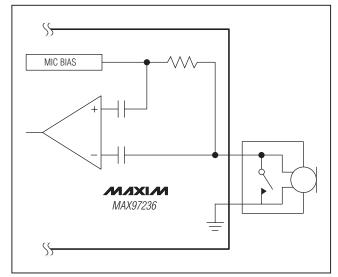


Figure 5. Passive Single-Button Hook Switch

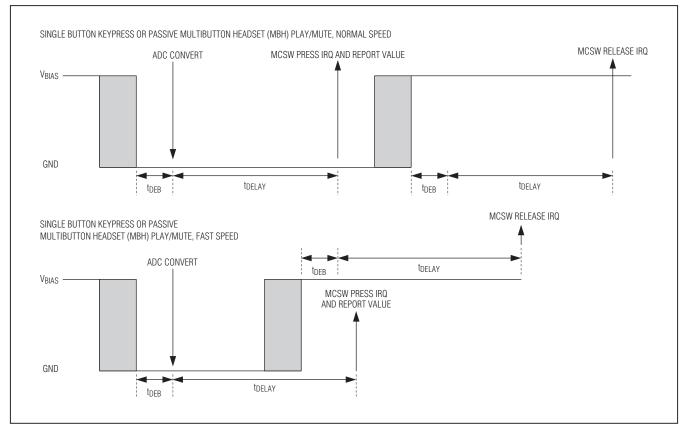


Figure 6. Single-Button, Passive Multibutton Hook Switch/Microphone Switch Timing

Passive Multibutton Headset (MBH)

A passive MBH consists of a microphone with numerous switches that connect different value resistors to ground. The switched resistor and the microphone bias resistor set up a voltage-divider that creates a unique voltage. The on-chip ADC then encodes the voltage and reports to the system.

A maximum 0.5Ω resistance between IC pins RING2 and SLEEVE and the headset is required for proper operation of the passive multibutton headset.

Figure 7 shows the circuit diagram of a passive MBH.

<u>Figure 8</u> shows the timing for a fast or normal speed keypress on a passive MBH. Note that a keypress develops a voltage that is above ground. The switch that shorts the microphone bias to ground is handled like the hook switch in the previous section.

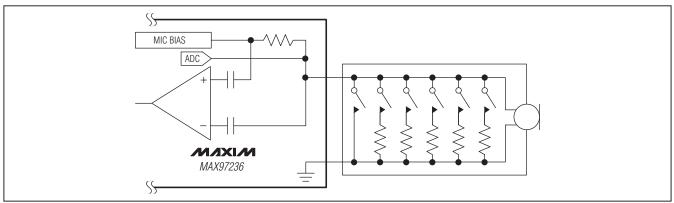


Figure 7. Passive MBH

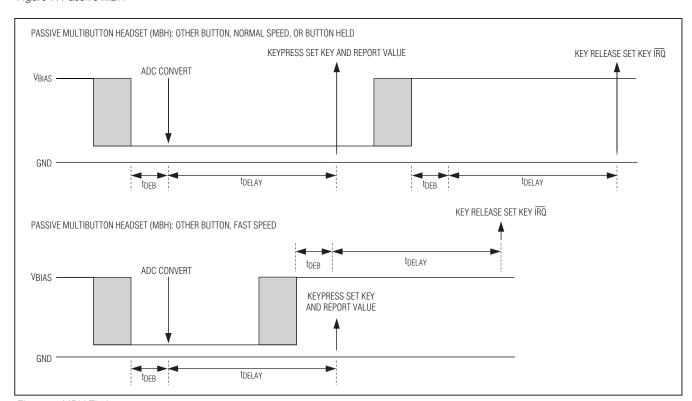


Figure 8. MBH Timing

Slow Jack Removal

Removing the headphone jack slowly can cause a false trigger of the key switch encoder because the right speaker between RING1 and RING2 shorts between microphone bias and ground. The programmable delay time must be set by the system to mask out this slow removal so that an interrupt does not flag until the JKIN status bit tells the system the jack is unplugged. Figure 9 shows the timing and interrupt reporting for a slow jack removal event. The act of microphone bias flying all the way up is the trigger for a microphone removal event. The <u>Jack Detection and Configuration Algorithm</u> section explains more about sensing jack removal.

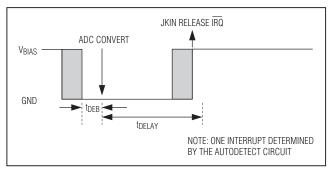


Figure 9. Slow Jack Removal Timing

Register and Bit Descriptions

Table 3. Register Map

REGISTER	В7	В6	B5	B4	В3	B2	B1	В0	ADDRESS	DEFAULT	R/W
Status1	JKIN	DDONE	VOL	_	MIC_IN	JACKSW	MCSW	MBH	0x00	0x00	R
Status2	LINE_L	LINE_R	HP_L	HP_R	JACKSWINC	KEY	_	_	0x01	0x00	R
Status3	_	_	_	_	_	_	G۱	1D	0x02	0x00	R
For Expansion	_	_	_	_	_	_	_	_	0x03	_	_
IRQ Mask1	IJKIN	IDDONE	IVOL	_	IMIC	JACKSW	IMCSW	IMBH	0x04	0x00	R/W
IRQ Mask2	ILINE_L	ILINE_R	IHP_L	IHP_R	IJACKSW	IKEY	_		0x05	0x00	R/W
For Expansion	_	_	_	_	_	_	_	_	0x06	_	_
Left Volume	L = R	MUTEL			LV	OL			0x07	0xC0	R/W
Right Volume	_	MUTER			RV	OL			0x08	0x40	R/W
Microphone	_	GAIN		MICF	}	BIAS	_		0x09	0x00	R/W
For Expansion				For e	expansion				0x0A	0x00	R/W
Vendor ID Register	ID — — — —						0x0B	0x90	R		
For Expansion				For e	expansion				0x0C	0x00	R/W
For Expansion				For e	expansion				0x0D	0x00	R/W
For Expansion				For e	expansion				0x0E	0x00	R/W
For Expansion				For e	expansion				0x0F	0x00	R/W
For Expansion				For e	expansion				0x10	0x00	R/W
For Expansion				For e	expansion				0x11	0x00	R/W
Keyscan Clock Divider 1				KEY_	DIV_HIGH				0x12	0x00	R/W
Keyscan Clock Divider 2		KEY_DIV_LOW							0x13	0x00	R/W
Keyscan Clock Divider ADC	KEY_DIV_ADC							0x14	0x00	R/W	
Keyscan Debounce				KE	EY_DEB				0x15	0x00	R/W
Keyscan Delay				KE	EY_DEL				0x16	0x00	R/W

Table 3. Register Map (continued)

	_			-							
REGISTER	B7	B6	B5	B4	В3	B2	B1	В0	ADDRESS	DEFAULT	R/W
Passive MBH Keyscan Data	PRESS	RANGE	KEYDATA					0x17	0x00	R	
DC Test Slew Control		DC_SLEW						0x18	0x00	R/W	
State Forcing	_	_	FORCE	FORCE STATE —				0x19	0x20	R/W	
AC Test Control	_	_	AC_RE	AC_REPEAT_ PULSE_WIDTH_ PULSE_AMP_				0x1A	0x05	R/W	
For Expansion	_	_	_	_	_	_	_	_	0x1B	_	_
For Expansion		_		_	_	_		_	0x1C	_	_
Enable1	SHDN	RESET	_	MIC_ BIAS	MIC_AMP	KS	_	_	0x1D	0x00	R/W
Enable2	LFTEN	RGHEN	VSEN	ZDEN	FAST	THRH	AU	TO	0x1E	0x00	R/W

Device Status Registers

Registers 0x00 and 0x01 are used to report the makeup of the inserted jack as well as report when a microphone switch has been pressed or the jack has been removed. The IC uses registers 0x00, 0x01, 0x02, and $\overline{\text{IRQ}}$ to report the status of various device functions. The Status_ register bits are set when their respective event occurs. Device status can be determined either by polling registers 0x00, 0x01, and 0x02 or configuring the $\overline{\text{IRQ}}$ to go low when specific events occur. Registers 0x04 and 0x05 determine which bits in the Status_ register trigger $\overline{\text{IRQ}}$ to go low. $\overline{\text{IRQ}}$ is cleared upon reading the register.

Table 4. Configuration and Device Status Registers

REGISTER	BIT	NAME	DESCRIPTION
	7	JKIN	Jack Detected JKIN changes state when the jack detect circuit senses a load at the left headphone output and SHDN = high 0 = No load at TIP. 1 = Load detected at TIP.
Status1	6	DDONE	Jack Configuration Detect Done DDONE changes state when the jack detect algorithm finishes and the jack configuration is known and reported in the status registers 0x00, 0x01, and 0x02. Resets after reading. 0 = Jack detect algorithm is not complete. 1 = Jack detection algorithm is complete.
(Read Only)	5	VOL	Volume Slew Complete VOL goes high after the headphone volume has slewed to its final programmed value. VOL sets every time a gain change is complete whether the gain change is positive or negative. Ramp the volume down and wait for VOL to set to ensure clickless turn off. Resets after reading. 0 = No volume slewing sequences have completed since any register was last read. 1 = Volume slewing complete.
	4	_	_

Table 4. Configuration and Device Status Registers (continued)

REGISTER	BIT	NAME	DESCRIPTION
	3	MIC_IN	Microphone Connected/Disconnected MIC_IN reports when a microphone is connected or removed. Set the MIC_INM interrupt mask to alert the system when the microphone load status has changed. 0 = Microphone is removed. 1 = Microphone is connected.
Status1 0x00 (Read Only)	2	JACKSW	JACKSW Status JACKSW reports the mechanical jack switch status. For an operational mechanical jack switch, JACKSW flags at the same time. If the switch is broken, or if the jack is not plugged in all the way, JACKSW and JKIN do not report the same value. The JACKSW bit also reports when a jack has been removed. Set the PIN5M interrupt mask bit to signal the system when the status of JACKSW changes. 0 = Mechanical jack switch reports no jack is connected. 1 = Mechanical jack switch shows that the jack is connected.
	1	MCSW	Microphone Switch Status MCSW goes high when the microphone bias goes low for the debounce period plus the delay period. This happens when a switch shorts across the microphone, pulling the micbias node down, indicating a keypress from a hook switch, ADC ≤ 4 LSB. Resets after reading. 0 = No change in microphone bias, no switch press. 1 = Microphone bias has been pulled to ground and debounced since the last status read. Debounce time set by KEY_DEB. Delay time set by KEY_DEL.
	0	MBH	Multibutton Headset Status MBH reports when a keypress from a multibutton headset is ready to be read. Resets after reading. 0 = No active keypress detected. 1 = Active keypress has been detected.
	7	LINE_L	Line-Level Load on TIP Detected 0 = Line-level load on TIP not detected. 1 = Line-level load on TIP detected.
	6	LINE_R	Line-Level Load on ROUT Detected 0 = Line-level load on RING1 not detected. 1 = Line-level load on RING1 detected.
Status	5	HP_L	Headphone Load on TIP Detected 0 = Headphone load on TIP not detected. 1 = Headphone load on TIP detected.
Status2 0x01 (Read Only)	4	HP_R	Headphone Load on RING1 Detected 0 = Headphone load on RING1 not detected. 1 = Headphone load on RING1 detected.
	3	JACKSWINC	JACKSW Incorrect JACKSWINC reports when there are inconsistencies between the mechanical switch and the electrical plug and unplug detection. The exception is when a plug-in occurs and SHDN is LOW. JACKSWINC does NOT clear when the STATUS register is read. JACKSW is checked at jack plug-in and unplug JACKSWINC is updated when JACKSW is checked. 0 = JACKSW reporting is correct and correlates with JKIN. 1 = JACKSW reporting is not correct and does not correlate with JKIN.

Table 4. Configuration and Device Status Registers (continued)

REGISTER	BIT	NAME	DESCRIPTION
Status2 0x01 (Read Only)	2	KEY	Passive Multibutton Headset KEY Status KEY reports when the passive multibutton has been pressed. Data is available in KEYDATA. See Figure 8. Resets after reading. 0 = No button pressed. 1 = Button has been pressed/released. Debounce and delay times have occurred.
	1	_	_
	0	_	_
	7	_	_
	6	_	_
	5	_	_
	4	_	
	3	_	_
Status3	2	_	_
0x02 (Read Only)	1	GND	Jack Common Location Identifier The two GND bits tell the system whether the jack's common connection is at RING2 or SLEEVE. GND is also used to indicate when a jack has been removed. 00 = No common connection sensed, jack has been removed or nothing has been inserted
	0	GIND	yet. 01 = The common jack connection is RING2. 10 = The common jack connection is SLEEVE. 11 = Common on both RING2 and SLEEVE.

Interrupt Mask Registers

The Interrupt Mask registers control which status bits flag a system interrupt. Setting an interrupt mask bit causes \overline{IRQ} to pull low whenever the target status bits set. The \overline{IRQ} output resets to high, after I²C register is read.

Table 5. Interrupt Mask Registers

REGISTER	BIT	NAME	DESCRIPTION
	7	IJKIN	Jack Detect Interrupt Enable 0 = Disabled 1 = Enabled
	6	IDDONE	Jack Configuration Detect Done Interrupt Enable 0 = Disabled 1 = Enabled
	5	IVOL	Volume Slew Interrupt Enable 0 = Disabled 1 = Enabled
	4	_	_
IRQ Mask1 0x04	3	IMIC	Microphone Interrupt Enable 0 = Disabled 1 = Enabled
	2	JACKSW	JACKSW Status Interrupt Enable 0 = Disabled 1 = Enabled
	1	IMCSW	Microphone Switch Interrupt Enable 0 = Disabled 1 = Enabled
	0	IMBH	Multibutton Release Status Interrupt Enable 0 = Disabled 1 = Enabled
	7	ILINE_L	Line-Level Load TIP Interrupt Enable 0 = Disabled 1 = Enabled
	6	ILINE_R	Line-Level Load RING1 Interrupt Enable 0 = Disabled 1 = Enabled
	5	IHP_L	Headphone Load TIP Interrupt Enable 0 = Disabled 1 = Enabled
IRQ Mask2 0x05	4	IHP_R	Headphone Load RING1 Interrupt Enable 0 = Disabled 1 = Enabled
	3	IJACKSW	JACKSW Incorrect Interrupt Enable 0 = Disabled 1 = Enabled
	2	IKEY	KEY Interrupt Enable 0 = Disabled 1 = Enabled
	1	_	_
	0	_	_

Headphone Volume Control Registers

The Headphone Volume registers independently control and report the gain of the left and right headphone amplifiers. Set B7 in Register 0x07 to have the right-channel gain track the left-channel gain.

Table 6. Headphone Volume Registers

REGISTER	BIT	NAME	DESCRIPTION						
Left Volume 0x07	7	L = R	Left/Right Tracking 0 = The right-channel volume control is independent of the left. 1 = The left and right volume controls track each other allowing for only one register to be written to change both channel volumes. Control both volume controls by writing to LVOL.						
	6	MUTEL/ MUTER	Headphone Mute 0 = Disable. 1 = Enable, output is muted.						
			L	eft/Right Headphon	e Output Volume Leve	el			
			HEX VALUE	GAIN (dB)	HEX VALUE	GAIN (dB)			
	5		0x00	-60	0x20	-25			
			0x01	-58	0x21	-24			
			0x02	-56	0x22	-23			
			0x03	-54	0x23	-22			
			0x04	-53	0x24	-21			
	4		0x05	-52	0x25	-20			
	4		0x06	-51	0x26	-19			
			0x07	-50	0x27	-24 -23 -22 -21 -20 -19 -18 -17 -16 -15 -14 -13 -12 -11 -10 -9 -8			
		LVOL/	0x08	-49	0x28	-17			
	3		0x09	-48	0x29	-16			
			0x0A	-47	0x2A	-15			
			0x0B	-46	0x2B	-14			
Left Volume/			0x0C	-45	0x2C	-13			
Right Volume			0x0D	-44	0x2D	-12			
0x07/0x08			0x0E	-43	0x2E	-11			
		RVOL	0x0F	-42	0x2F	-10			
			0x10	-41	0x30	-9			
	0		0x11	-40	0x31	-8			
	2		0x12	-39	0x32	-7			
			0x13	-38	0x33	-6			
			0x14	-37	0x34	-5			
			0x15	-36	0x35	-4			
			0x16	-35	0x36	-3			
	1		0x17	-34	0x37	-2			
	ı		0x18	-33	0x38	-1			
			0x19	-32	0x39	0			
			0x1A	-31	0x3A	1			
			0x1B	-30	0x3B	2			
			0x1C	-29	0x3C	3			
	0		0x1D	-28	0x3D	4			
			0x1E	-27	0x3E	5			
			0x1F	-26	0x3F	6			

Microphone Bias Control and Gain Register

The Microphone Bias Control and Gain register controls which microphone bias voltage and bias resistors are used as well as the microphone amplifier gain.

Table 7. Microphone Bias and Gain Register

REGISTER	BIT	NAME	DESCRIPTION
	7	_	_
	6	GAIN	Microphone Preamplifier Gain Select 0 = 12dB 1 = 24dB
	5		Microphone Bias Resistor Select $000 = 2.2 k\Omega$
Microphone 0x09	4	MICR	$001 = 2.6k\Omega$ $010 = 3.0k\Omega$
0x09	3		011 = Bypassed 1XX = High impedance (sleep mode)
	2	BIAS	Microphone Bias Voltage Select 0 = 2.0V 1 = 2.6V
	1	_	_
	0	_	_

Vendor ID Register

Vendor ID bits are shown in Table 8.

Table 8. Vendor ID Register

REGISTER	BIT	NAME	DESCRIPTION
	7		
Vendor ID Register 0x0B	6	ID	Vendor ID 0x9 = Maxim's vendor ID
	5		
	4		
	3	_	
	2	_	
	1	_	
	0	_	

Keyscan Clock Divider Registers

The Keyscan Clock Divider register sets the clock frequency that is used for the conversion clock for the keyscan 1kHz generator.

Table 9. Keyscan Clock Divider Registers

REGISTER	BIT	NAME	DESCRIPTION
	7		Keyscan Clock Divider
	6		The keyscan 1kHz clock is generated by dividing down the frequency of
Keyscan Clock Divider 1/2 0x12/0x13	5		EXTCLK. The divider is set with the 16 bits contained within registers 0x12 and 0x13, where 0x12 is the high byte and 0x13 is the low byte.
	4	KEY_DIV_HIGH/ KEY_DIV_LOW	Since 1kHz (1ms) is desired, then:
	3		$N = f_{ N }/2kHz$
	2		e.g., $f_{IN} = 20MHz$, then N = 10,000
	1		e.g., f _{IN} = 1MHz, then N = 500 e.g., f _{IN} = 19.2MHz, then N = 9600
	0		For the low input frequencies, resolution is about 0.2%.

Keyscan Divider ADC Register

The Keyscan ADC Clock Divider register sets the clock frequency that is used for the conversion clock for the keyscan 6-bit ADC.

Table 10. Keyscan ADC Clock Divider Registers

REGISTER	BIT	NAME	DESCRIPTION
	7		Keyscan ADC Clock Divider
	6		The keyscan ADC clock is generated by dividing down the frequency of EXTCLK. The divider is set with the 8 bits contained within register 0x14. Since 100kHz (10 μ s) is desired, then: $N = f_{IN}/200kHz$ e.g., $f_{IN} = 20MHz$, then N = 100
Keyscan	5		
Clock Divider ADC 0x14	4	VEV DIV ADO	
	3	KEY_DIV_ADC	
	2		e.g., f _{IN} = 1MHz, then N = 5
	1		e.g., f _{IN} = 19.2MHz, then N = 96
	0		For the low input frequencies, resolution is about 20%.

Keyscan Debounce Register

The Keyscan Debounce register controls the debounce time when a keypress is detected. See Figure 6.

Table 11. Keyscan Debounce Register

REGISTER	BIT	NAME	DESCRIPTION
	7		
	6		
	5	KEY_DEB	Keyscan Debounce Register
Keyscan Debounce	4		Debounce time set from 1ms to 256ms in 1ms increments. The programmed code plus one represents the debounce time directly.
0x15	3		t _{DEB} = KEY_DEB + 1
OX 10	2		e.g., code 0x13 represents 20ms of debounce.
	1		
	0		

Keyscan Delay Register

The Keyscan Delay register sets the timeout that the microphone button press is masked from the system. At the end of the delay time, the IC checks to see if a microphone is still present. If the microphone is present, the system is alerted by setting the MCSW bit in the status register flagging an interrupt if IMCSW is set. If the microphone is not present after the delay time, the system is flagged with an interrupt by setting MICROPHONE_IN signifying that the microphone has been removed and no keypress was made.

Table 12. Keyscan Delay Register

REGISTER	BIT	NAME	DESCRIPTION
	7		
	6		
	5	KEY_DEL	Keyscan Delay Register
Keyscan	4		Delay time set from 4ms to 1024ms in 4ms increments. The programmed code
Delay 0x16	3		plus one multiplied by 4ms represents the delay time. tDELAY = (KEY_DEL + 1) x 4ms
0,710	2		e.g., code 0x63 represents 400ms of delay.
	1		
	0		

Passive Multibutton Keyscan Data Register

The Keyscan Data register contains the data read from a keypress after the 6-bit ADC encodes the input voltage level. The read keypress could come from a single switch or a passive multibutton device.

Table 13. Keyscan Data Register

REGISTER	BIT	NAME	DESCRIPTION
	7	PRESS	Release Tells if a KEY status was PRESS or RELEASE. 0 = Key release. 1 = Keypress.
Passive MBH Keyscan Data	6	RANGE	0 = Coarse range. 1 = Fine range.
0x17	5		
(Read Only)	4		Keyscan Data
	3	KEYDATA	B6–B0 are read-only bits that contain the data read from a passive keypress
	2	RETUATA	that shorts the microphone to ground. There is a coarse range (10mV/LSB) and a fine range (2mV/LSB). See Figure 7 and the <i>Passive Multibutton Headset</i>
	1		(MBH) section.
	0		

Ramp Test Slew Control

The ramp test slew control programs the period of the jack configuration algorithm's ramp test. Slow slew rates ensure test inaudibility, but increase test time to complete the configuration algorithm.

Table 14. Ramp Test Slew Control

REGISTER	BIT	NAME	DESCRIPTION
	7		
	6		
DO T . O	5		
DC Test Slew Control	4	DC SLEW	DC Slew Control Drogram the DC test claw rate from 5 12ms to 1205 6ms in 5 12ms stone
0x18	3	DC_SLEW	Program the DC test slew rate from 5.12ms to 1305.6ms in 5.12ms steps. Recommend value to be used is 0x04 to 0x08.
0.210	2		Trooprinteria value to be used to exert to exect.
	1		
	0		

Load State Forcing

Use the Load State Forcing register to force a state and ignore the results of the jack detection algorithm. It forces the required blocks to be on (bypassing the Enable registers).

Table 15. Load State Forcing

REGISTER	BIT	NAME	DESCRIPTION
	7	_	_
	6	_	_
State Forcing 0x19	5	FORCE	Load State Force Enable 0 = Forces the IC into a configuration defined by 0b4–0b0. 1 = State forcing disabled.

Table 15. Load State Forcing (continued)

REGISTER	BIT	NAME	DESCRIPTION		
	4		State Value Bits 0b4–0b0 programs the configuration of the IC. The columns show all the possible configurations.		
			CODE [B4:B0]	STATE (F = Float, L = Left Audio, R = Right Audio, G = Ground, M = Microphone)	
			0x01	FFFF	
	3		0x02	LRGM	
	3		0x03	03 LRMG	
		STATE	0x07	LRGG_AC	
State Forcing 0x19			0x08	LRGF	
0.19	2		0x09	LFGF	
			0x0A	FRGF	
		0x0C	LGGM		
		0x0D 0x0E 0x0F	0x0D	LGMG	
			0x0E	LLGM	
	1		LLMG		
	I		0x10	LFGM	
			0x11	LFMG	
			0x12	LRGG_DC	
	0		0x13	LFGG	
			0x14	FRGG	

Pulse Test Hardware Settings

The Jack Detect Test Hardware Settings register programs the amplitude and width of the pulse used in the jack detection tests and jack insertion algorithm.

Table 16. Jack Detect Test Hardware Settings

REGISTER	BIT	NAME	DESCRIPTION
	7	_	_
	6	_	
	5	AC_REPEAT1	AC_Repeat 00 = 1, 01 = 3, 10 = 5, 11 = 7.
	4	AC_REPEAT0	Programs number of pulses sent for each jack detection test.
AC Test Control	3	PULSE_WIDTH1	Pulse Width - 00 = 50µs, 01 = 100µs, 10 = 150µs, 11 = 300µs. Test 1 and 4 pulse wid
0x1A	2	PULSE_WIDTH0	is fixed at 10 μ s.
	1	PULSE_AMP1	Pulse Amplitude For tests 1 and 4, pulse amplitude is 00 = 25mV, 01 = 50mV, 10 = 100mV,
	0	PULSE_AMP0	11 = 200mV. Tests 6, 7, and 8 pulse amplitude is 00 = 37mV, 01 = 75mV, 10 = 150mV, 11 = 220mV.

Enable Registers

The Enable_ registers contain all of the bits that control the separate functional blocks for the IC. The system can either directly control these bits, or it can allow the IC to automatically configure itself and report in the Enable_ register which blocks are enabled. When the AUTO bits (B1, B0) are set to 01 or 10, the Enable_ registers are read-only (except the SHDN and SLEEP bits). The block enable bits need to be set to sense a jack removal. The jack removal circuitry is active after the jack configurations detect algorithm has completed.

Table 17. Enable Registers

REGISTER	BIT	NAME	DESCRIPTION
Enable1 0x1D	7	SHDN	Full Device Shutdown Control SHDN turns the IC on and off. When SHDN is low, the device is in shutdown mode and the jack insertion detect circuitry is active. Pull SHDN high to turn on the device and run the jack configuration detect algorithm. Typically, SHDN is held low until the system gets an interrupt from the IC, indicating that a jack has been inserted. The system then pulls SHDN high. 0 = The IC is in shutdown mode with jack detection circuitry active. 1 = The IC is active. The jack configuration algorithm runs immediately after a load has been detected.
	6	RESET	RESET Jack Detection Cycle RESET (low → high → low) to repeat the jack detection and configuration algorithm.

Table 17. Enable Registers (continued)

REGISTER	BIT	NAME	DESCRIPTION
	5	_	
	4	MIC_BIAS	Microphone Bias Enable/Status Set MIC_BIAS to enable the microphone block. This bit is read-only when AUTO (0b0 or 0b1) is set. 0 = Microphone bias is disabled. 1 = Microphone bias is enabled.
Enable1 0x1D	3	MIC_AMP	Microphone Amplifier Enable/Status Set MIC_AMP to enable the microphone amplifier. This bit is read-only when AUTO (0b0 or 0b1) is set. 0 = Microphone amplifiers are disabled. 1 = Microphone amplifiers are enabled.
	2	KS	Keyscan Enable/Status KS enables the circuitry that decodes passive multibutton keypad or simple microphone switch. This bit is read only when AUTO (0b0 or 0b1) is set. 0 = Keyscan ADC is disabled. 1 = Keyscan ADC is enabled.
	1	_	_
	0	_	_
Enable2	7	LFTEN	Left Headphone Enable/Status Set LFTEN to enable the left channel of the DirectDrive headphone amplifier. This bit is read-only when AUTO (0b0 or 0b1) is set. 0 = Headphone amplifier left channel is disabled. 1 = Headphone amplifier left channel is enabled.
0x1E	6	RGHEN	Right Headphone Enable/Status Set RGHEN to enable the left channel of the DirectDrive headphone amplifier. This bit is read-only when AUTO (B0) is set. 0 = Headphone amplifier right channel is disabled. 1 = Headphone amplifier right channel is enabled.

Table 17. Enable Registers (continued)

REGISTER	BIT	NAME	DESCRIPTION
	5	VSEN	Volume Adjustment Slewing Volume changes are smoothed by stepping through intermediate steps. VSEN also ensures that the volume automatically ramps from the minimum setting to the programmed value at turn-on and back to the minimum value at turn-off. 0 = Enabled. 1 = Disabled.
	4	ZDEN	Zero-Crossing Detection ZDEN holds volume changes until there is a zero-crossing in the audio signal. This reduces clicks during volume changes (zipper noise). If no zero-crossing is detected within 100ms, the volume change is forced. 0 = Enabled. 1 = Disabled.
	3	FAST	Jack Insertion Polling Speed A fast polling speed tests for a jack insertion 3 times per second, while a slow polling speed tests for jack insertion every 2 seconds. Setting the polling speed to slow mode saves shutdown power consumption while the mechanical JACKSW switch is operational. 0 = Slow polling mode, 2s delay between polls. 1 = Fast polling mode, 333ms delay between polls.
Enable2 0x1E	2	THRH	Class H Threshold Select THRH selects the threshold at which the power supplies switch from ±0.9V to ±1.8V. A higher threshold allows the IC's output stage to be powered from ±0.9V for a higher percentage of the audio waveform, decreasing power dissipation at the expense of dynamic distortion. 0 = Low threshold. 1 = High threshold.
	1	ALITO	Automatic Mode Select Set AUTO to allow the IC to enable functional blocks depending on the load. In auto mode, the user merely reads the status of registers 0x1D and 0x1E to find out what blocks are enabled. Setting AUTO makes bits register 0x1D and 0x01E read-only (except SHDN and SLEEP). Clear AUTO to give the system control of what functional blocks are active. The user needs to allow the jack configuration detect algorithm to complete before enabling functional blocks.
	0	AUTO	00 = User controls which functional blocks are on. Registers 0x1D and 0x1E are R/W. 01 = The IC enables functional blocks automatically depending on the results of the jack configuration detect algorithm after \$\overline{S}HDN\$ is set. 10 = The IC enables functional blocks automatically depending on the results of the jack configuration detect algorithm regardless of whether \$\overline{S}HDN\$ is set. \$\overline{S}HDN\$ must go to high to enable audio playback.

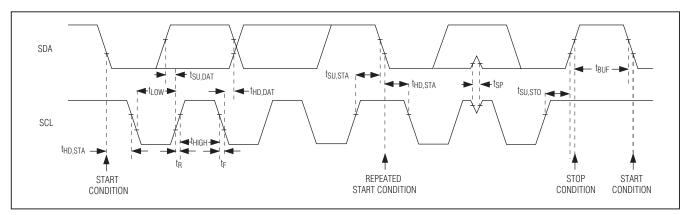


Figure 10. I²C Interface Timing Diagram

I²C Serial Interface

The IC features an I2C/SMBus™-compatible. 2-wire serial interface consisting of a serial-data line (SDA) and a serial-clock line (SCL). SDA and SCL facilitate communication between the IC and the master at clock rates up to 400kHz. Figure 10 shows the 2-wire interface timing diagram. The master generates SCL and initiates data transfer on the bus. The master device writes data to the IC by transmitting the proper slave address followed by the register address and then the data word. Each transmit sequence is framed by a START (S) or REPEATED START (Sr) condition and a STOP (P) condition. Each word transmitted to the IC is 8 bits long and is followed by an acknowledge clock pulse. A master reading data from the IC transmits the proper slave address followed by a series of nine SCL pulses. The IC transmits data on SDA in sync with the master-generated SCL pulses. The master acknowledges receipt of each byte of data. Each read sequence is framed by a START or REPEATED START condition, a not acknowledge, and a STOP condition. SDA operates as both an input and an open-drain output. A pullup resistor, typically greater than 500Ω , is required on SDA. SCL operates only as an input. A pullup resistor, typically greater than 500Ω , is required on SCL if there are multiple masters on the bus, or if the single master has an open-drain SCL output. Series resistors in line with SDA and SCL are optional. Series resistors protect the digital inputs of the IC from high voltage spikes on the bus lines, and minimize crosstalk and undershoot of the bus signals.

Bit Transfer

One data bit is transferred during each SCL cycle. The data on SDA must remain stable during the high period of the SCL pulse. Changes in SDA while SCL is high are control signals. See the *START and STOP Conditions* section.

START and STOP Conditions

SDA and SCL idle high when the bus is not in use. A master initiates communication by issuing a START condition. A START condition is a high-to-low transition on SDA with SCL high. A STOP condition is a low-to-high transition on SDA while SCL is high (Figure 11). A START condition from the master signals the beginning of a transmission to the IC. The master terminates transmission and frees the bus by issuing a STOP condition. The bus remains active if a REPEATED START condition is generated instead of a STOP condition.

Early STOP Conditions

The IC recognizes a STOP condition at any point during data transmission except if the STOP condition occurs in the same high pulse as a START condition. For proper operation, do not send a STOP condition during the same SCL high pulse as the START condition.

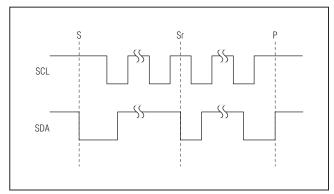


Figure 11. START, STOP, and REPEATED START Conditions

SMBus is a trademark of Intel Corp.

Slave Address

The slave address is defined as the 7 most significant bits (MSBs) followed by the read/write bit. The IC has an address of 0x80. The 7 most significant bits are 100000. Setting the read/write bit to 1 (slave address = 0x81) configures the IC for read mode. Setting the read/write bit to 0 (slave address = 0x80) configures the IC for write mode. The address is the first byte of information sent to the IC after the START condition.

Acknowledge

The acknowledge bit (ACK) is a clocked ninth bit that the IC uses to handshake receipt each byte of data when in write mode (Figure 12). The IC pulls down SDA during the entire master-generated ninth clock pulse if the previous byte is successfully received. Monitoring ACK

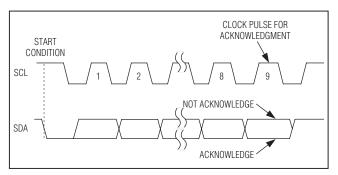


Figure 12. Acknowledge

allows for detection of unsuccessful data transfers. An unsuccessful data transfer occurs if a receiving device is busy or if a system fault has occurred. In the event of an unsuccessful data transfer, the bus master retries communication. The master pulls down SDA during the 9th clock cycle to acknowledge receipt of data when the IC is in read mode. An acknowledge is sent by the master after each read byte to allow data transfer to continue. A not-acknowledge is sent when the master reads the final byte of data from the IC, followed by a STOP condition.

Write Data Format

A write to the IC includes transmission of a START condition, the slave address with the $R\overline{W}$ bit set to 0, one byte of data to configure the internal register address pointer, one or more bytes of data, and a STOP condition. Figure 13 illustrates the proper frame format for writing one byte of data to the IC. Figure 14 illustrates the frame format for writing n bytes of data to the IC.

The slave address with the R/\overline{W} bit set to 0 indicates that the master intends to write data to the IC. The IC acknowledges receipt of the address byte during the master-generated 9th SCL pulse.

The second byte transmitted from the master configures the IC's internal register address pointer. The pointer tells the IC where to write the next byte of data. An acknowledge pulse is sent by the IC upon receipt of the address pointer data.

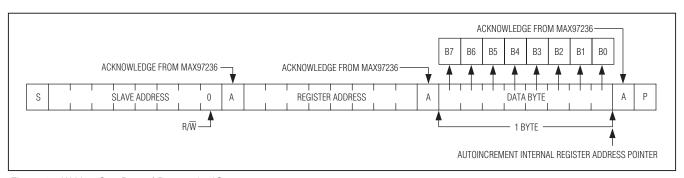


Figure 13. Writing One Byte of Data to the IC

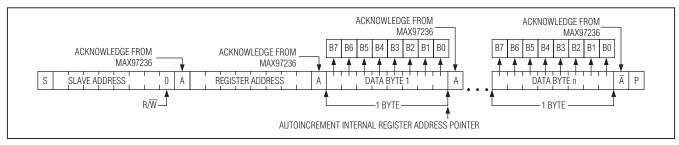


Figure 14. Writing n Bytes of Data to the IC

The third byte sent to the IC contains the data that is written to the chosen register. An acknowledge pulse from the IC signals receipt of the data byte. The address pointer autoincrements to the next register address after each received data byte. This autoincrement feature allows a master to write to sequential registers within one continuous frame. The master signals the end of transmission by issuing a STOP condition. Register addresses greater than 0x0C are reserved. Do not write to these addresses.

Read Data Format

Send the slave address with the R/\overline{W} bit set to 1 to initiate a read operation. The IC acknowledges receipt of its slave address by pulling SDA low during the 9th SCL clock pulse. A START command followed by a read command resets the address pointer to register 0x00.

The first byte transmitted from the IC is the content of register 0x00. Transmitted data is valid on the rising edge of SCL. The address pointer autoincrements after each read data byte. This autoincrement feature allows all registers to be read sequentially within one continuous

frame. A STOP condition can be issued after any number of read data bytes. If a STOP condition is issued followed by another read operation, the first data byte to be read is from register 0x00.

The address pointer can be preset to a specific register before a read command is issued. The master presets the address pointer by first sending the IC's slave address with the R/ \overline{W} bit set to 0 followed by the register address. A REPEATED START condition is then sent followed by the slave address with the R/ \overline{W} bit set to 1. The IC then transmits the contents of the specified register. The address pointer autoincrements after transmitting the first byte.

The master acknowledges receipt of each read byte during the acknowledge clock pulse. The master must acknowledge all correctly received bytes except the last byte. The final byte must be followed by a not acknowledge from the master and then a STOP condition. Figure 15 illustrates the frame format for reading one byte from the IC. Figure 16 illustrates the frame format for reading multiple bytes from the IC.

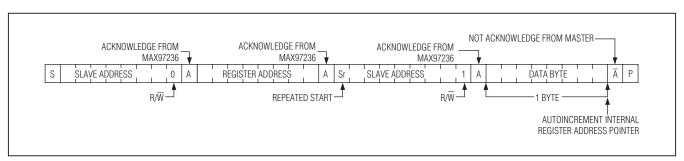


Figure 15. Reading One Byte of Data from the IC

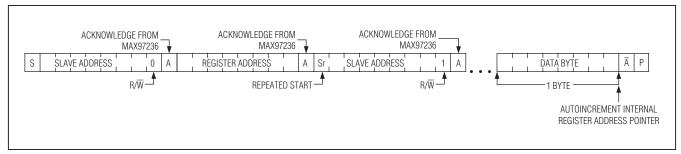


Figure 16. Reading n Bytes of Data from the IC

Applications Information

Power Modes

The power modes of the IC are controlled by the $\overline{\text{SHDN}}$ bit. The three power modes include detection, normal operating, and standby.

Detection mode occurs when no jack has been plugged in, $\overline{SHDN} = RESET = 0$. Once a jack is plugged in and detected, the IC enters normal operating mode after \overline{SHDN} transitions from 0 to 1. While in normal operating mode, pull \overline{SHDN} low to put the device in standby mode. Pull RESET high then low to reset the jack detection and configuration.

Standby mode leaves the key encoder active to pick up a keypress event if the IC has completed jack detection prior to standby mode. A weak pullup voltage is put across the microphone to look for a hook switch press. Once a keypress event occurs, an interrupt flags, and the IC enters detection mode after SHDN transitions high.

Power Domains

MVDD power domain:

Microphone bias, switches, ESD, and jack detection tests 2 to 9.

V_{DD} power domain:

Charge pump, digital block, ADC, mic amp, and jack detection test 1.

Power-Up/-Down Sequence

The IC needs V_{DD} and MVDD to operate correctly.

Turning off one supply voltage during a mode might prevent proper operation of the IC.

The power-up sequence is:

- Apply V_{DD}
- Apply MVDD
- Set AUTO to 01 (register 0x1E, bit 0)

There are a few different ways to power-up/-down depending on how autonomous you want the IC to operate and whether the jack is plugged in or not. The AUTO bits are in register 0x1E, bits 0 and 1. The three methods for getting the IC running are:

 AUTO = 0x00: The IC detects a jack plug-in and set JKIN, but does not run the configuration detect until SHDN is pulled high. After the configuration is detected, the IC waits for the system to turn on the appropriate enable bits.

- AUTO = 0x01: The IC detects a jack plug-in and set JKIN, but does not run the configuration detect until SHDN is pulled high. After the configuration detect is run, the IC automatically sets the appropriate enable bits to be able to drive all loads for the found cable.
- AUTO = 0x02: The IC detects a jack plug-in, sets JKIN, and automatically runs the configuration detect. After the configuration detect is run, the IC automatically sets the appropriate enable bits to be able to drive all loads for the found cable. However, the amplifiers do not actually turn on until SHDN is pulled high. The IC completes detection and waits in standby mode until SHDN is pulled high.

Ensure that RESET = 0 to enable the jack detect plug-in test signal.

Power-Up, AUTO = 0x00 or 0x01:

- 1) Set IDDONE and IJACKSW and IJKIN so that an interrupt flags when something is plugged in and the detection is done.
- 2) Wait for IRQ.
- 3) Wait for JACKSW to set.
- 4) Pull SHDN high.
- 5) Detection is done when DDONE sets.

If AUTO = 0x00:

- 1) Read the Status registers to find out what was detected.
- 2) System makes a decision about what to enable.
- 3) System sets the appropriate enable bits.
- 4) Set the volume register to the appropriate setting if audio is present.

If AUTO = 0x01:

- 1) Read the Status registers to find out what was detected.
- 2) The appropriate enable bits automatically set.
- 3) Read the Enable1 and Enable2 registers to see what was turned on.
- 4) Set the volume register to the appropriate setting if audio is present.

Power-Up, AUTO = 0x02:

- 1) Wait for JKIN to set.
- 2) Detection runs automatically, so wait for DDONE to set.
- 3) Read the Status registers to find out what was detected.
- 4) The IC is automatically placed in standby mode after detection is done.
- 5) Pull SHDN high to turn on the IC.
- 6) The appropriate enable bits were automatically set because AUTO = 0x02.
- 7) Read the Enable1 and Enable2 registers to see what was turned on.

When AUTO = 0x01 or 0x02, the IC automatically enables the required blocks according to what has been detected. In case AUTO = 0x00, it is required that all the correct blocks are enabled for unplug detection to work properly. Table 18 correlates the status bits with the enable bits for the blocks that are (need to be) enabled for proper operation.

Power-Down, All AUTO Settings:

If audio is playing and $\overline{VSEN} = 0$:

- 1) Set the headphone volume register mute bits or set code 0x00 as the volume.
- The VOL bit is set when the volume slew is done. Make sure IVOL is set so that an interrupt is flagged.
- 3) Pull SHDN low to go into standby mode; the current jack case is remembered. Cycle RESET (low → high → low) to run jack detection and configuration again.

If audio is not playing:

 Set VSEN = 1 to disable volume slewing. If this is not done, the volume slew down at a rate of 1ms per volume step.

Table 18. Status Bits Relation to Enable Bits

STATUS BIT	ENABLE BIT
MIC_IN	MIC_BIAS MIC_AMP KS
LINE_L	LFTEN
LINE_R	RGHEN
HP_L	LFTEN
HP_R	RGHEN

- 2) Set the headphone volume register mute bits or set code 0x00 as the volume, and the amplifiers mute immediately.
- 3) Pull SHDN to 0 to go to standby mode; the current jack case is remembered. Cycle RESET (low → high → low) to run jack detection and configuration again.

PCB Layout and Grounding

Proper layout and grounding are essential for optimum performance. Use large traces for the power-supply inputs and amplifier outputs to minimize losses due to parasitic trace resistance, as well as route heat away from the device. Good grounding improves audio performance, minimizes crosstalk between channels, and prevents switching noise from coupling into the audio signal. Connect PGND and GND together at a single point on the PCB. Route PGND and all traces that carry switching transients away from GND, and the traces and components in the audio signal path.

Place the charge-pump capacitors as close as possible to the device. Bypass PVDD and PVSS with a $1\mu F$ capacitor to PGND. Place the bypass capacitors as close as possible to the device.

Route the pins that connect to the jack on wide, low-impedance traces whenever possible. RING2 or SLEEVE ends up being the load's ground connection; ground impedance causes excess crosstalk and noise pickup.

Route the EXTCLK traces away from low-level audio input nodes and the microphone bias bypass connection to keep the audio as noise free as possible.

PGND and GND pins need to have as low an impedance connection to the ground plane. This means liberal use of vias and a solid ground plane.

The maximum resistance between the pins TIP and RING1 to the headphone jack should not exceed 3Ω .

The maximum resistance between RING2 and SLEEVE to the headphone jack should be 0.5Ω or better. RING2 or SLEEVE is used as the common connector in a headset or headphone. Any impedance on this path decreases crosstalk performance.

Power-Supply Bypassing

A bulk 10 μ F capacitor is required for proper charge-pump operation. The capacitors are readily available in 0603 packages in the necessary voltage rating. Bypass V_{DD} to PGND with 10 μ F.

Component Selection and LayoutCharge-Pump Capacitors

The charge pump requires three capacitors: PVDD, PVSS, and the flying capacitor between C1N and C1P. It is recommended that these all remain the same value.

Capacitance values of $1\mu F$ are recommended. Larger value capacitors can be used to lower power-supply ripple. Do not use charge-pump caps greater than $3.3\mu F$. See <u>Table 19</u> for a detailed description for each component value.

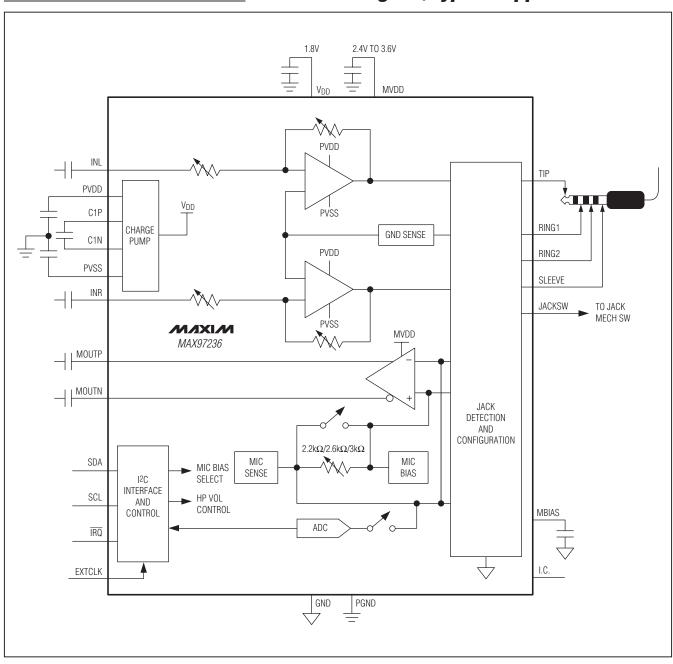
Table 19. Recommended Component Values

COMPONENT	RECOMMENDED VALUE	DETAILS
Charge-pump capacitors	1μF, X5R, 6.3V or greater voltage rating or better	The capacitor needs low ESR to achieve the required charge-pump output impedance. If the charge-pump output impedance is too high, the headphone amplifier cannot deliver the stated output power. A larger capacitor does not completely charge in one switching cycle. A smaller capacitor does not hold enough charge. Thus, it is highly recommended to use the suggested value.
V _{DD} capacitor	C1: 1µF to 10µF, X5R, 6.3V or better C2: 0.01nF to 0.1µF, X5R, 6.3V minimum	C1: A smaller values helps on the ESD robustness. C2: Is not a must-have capacitor, but still recommended. This capacitor helps improve the RF immunity of the IC.
Audio input capacitors	1μF, 6.3V, X5R or better	Lower capacitance creates a highpass filter due to the input impedance of the IC.
Microphone input capacitors	1μF, 6.3V, X5R or better	_
EMI filter capacitors	33pF	_
EMI filter ferrite bead	Murata BLM15BB220	_

_____Chip Information

PROCESS: BICMOS

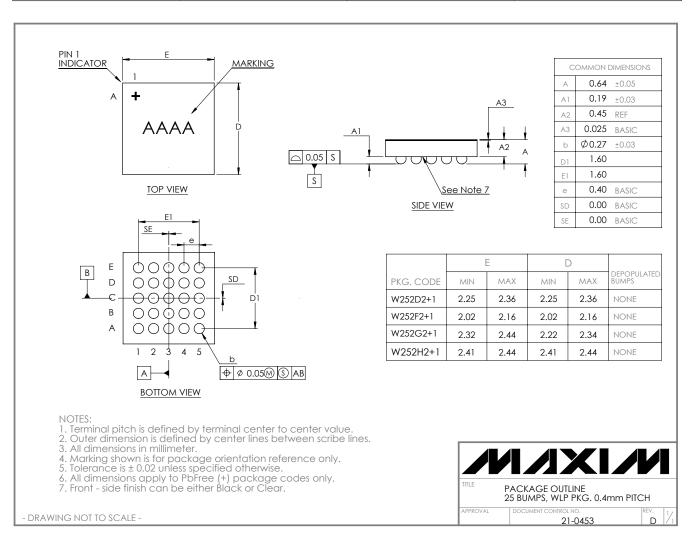
Functional Diagram/Typical Application Circuit



Package Information

For the latest package outline information and land patterns (footprints), go to www.maxim-ic.com/package. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
25-Bump WLP	W252G2+1	<u>21-0453</u>	Refer to Application Note 1891



Revision History

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	3/11	Initial release	_
1	5/11	Widened IRQ spec	2
2	10/11	Updated Jack Configuration Detection and Headphone Volume Control Registers sections	10, 12, 13, 22, 24, 35
3	11/11	Deleted the ESD Protection parameter from the Electrical Characteristics Table	5

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